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In the Claims:

Kindly amend the claims as follows:

1. (Currently amended) A method for manufacturing an anisotropic conductive sheet comprising:  
  
step A; etching through a monocrystal silicon wafer by a deep reactive ion etching so as to form a part having a bending leaf spring shape such that planes of said formed leaf spring are parallel to a cross section of said wafer,  
  
step B; forming a silicon spring electrode by forming a conductive layer on a surface of said part having the bending leaf spring shape formed in step A, and  
  
step C; inserting a plurality of said silicon spring electrodes formed in step B respectively into through holes of a soft plastic sheet such that said spring electrodes are clamped and fixed to said soft plastic sheet and do not extend out of the holes during operation.